Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.5 EP)
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.22E-02	86.2	862000	37.98	379768
Thermosets	Epoxy resin	Proprietary	1.55E-03	6.0	60000	2.64	26434
Thermosets	Phenol resin	Proprietary	1.55E-03	6.0	60000	2.64	26434
Other inorganic materials	Metal Hydroxide	Proprietary	3.87E-04	1.5	15000	0.66	6608
Other inorganic materials	Carbon black	1333-86-4	7.74E-05	0.3	3000	0.13	1322
Subtotal			2.58E-02	100.00	1000000	44.06	440566

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.82 E-02	99.25	992500	48.13	481327
Copper & its alloys	Chromium	7440-47-3	8.52 E-05	0.30	3000	0.15	1455
Copper & its alloys	Tin	7440-31-5	7.10 E-05	0.25	2500	0.12	1212
Copper & its alloys	Zinc	7440-66-6	5.68 E-05	0.20	2000	0.10	970
Subtotal			2.84 E-02	100.00	1000000	48.50	484964

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.10 E-05	100.0	1000000	0.12	1212

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.30 E-03	100.0	1000000	2.22	22199

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.00 E-05	100.0	1000000	0.15	1537

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.70 E-03	100.0	1000000	4.61	46106

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.47 E-04	73.40	734000	0.25	2507
Thermoset	Epoxy Resin	Proprietary	3.67 E-05	18.35	183500	0.06	627
Other inorganic materials	Metal oxide	Proprietary	5.50 E-06	2.75	27500	0.01	94
Others	Curing and hardening agent	Proprietary	5.50 E-06	2.75	27500	0.01	94
Other organic materials	Gamma Butyrolactone	96-48-0	5.50 E-06	2.75	27500	0.01	94
Subtotal			2.00 E-04	100.0	1000000	0.34	3415

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.86 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary